



SD-106S-ACP11  
W28.98xD28.80xH2.87

PIN 数(Number of contacts) : 9+2PIN

耐电压(Withstand voltage) : 250V AC for 1 min

操作方式(Operation mode): 自弹式/PUSH PUSH

操作寿命(Operation life): 5,000 Cycles Min

温度范围(Operating temp): -40°C TO +80°C

焊接温度(Welding temperature): 260±5° 5s

额定负荷(Rated load): 0.5A PERP IN.

焊接方式(Welding mode): 贴片式/SMT

接触电阻(Contact resistance): 100mΩ max.

包装方式(Packaging method): 卷带/Tape & Reel (TR)

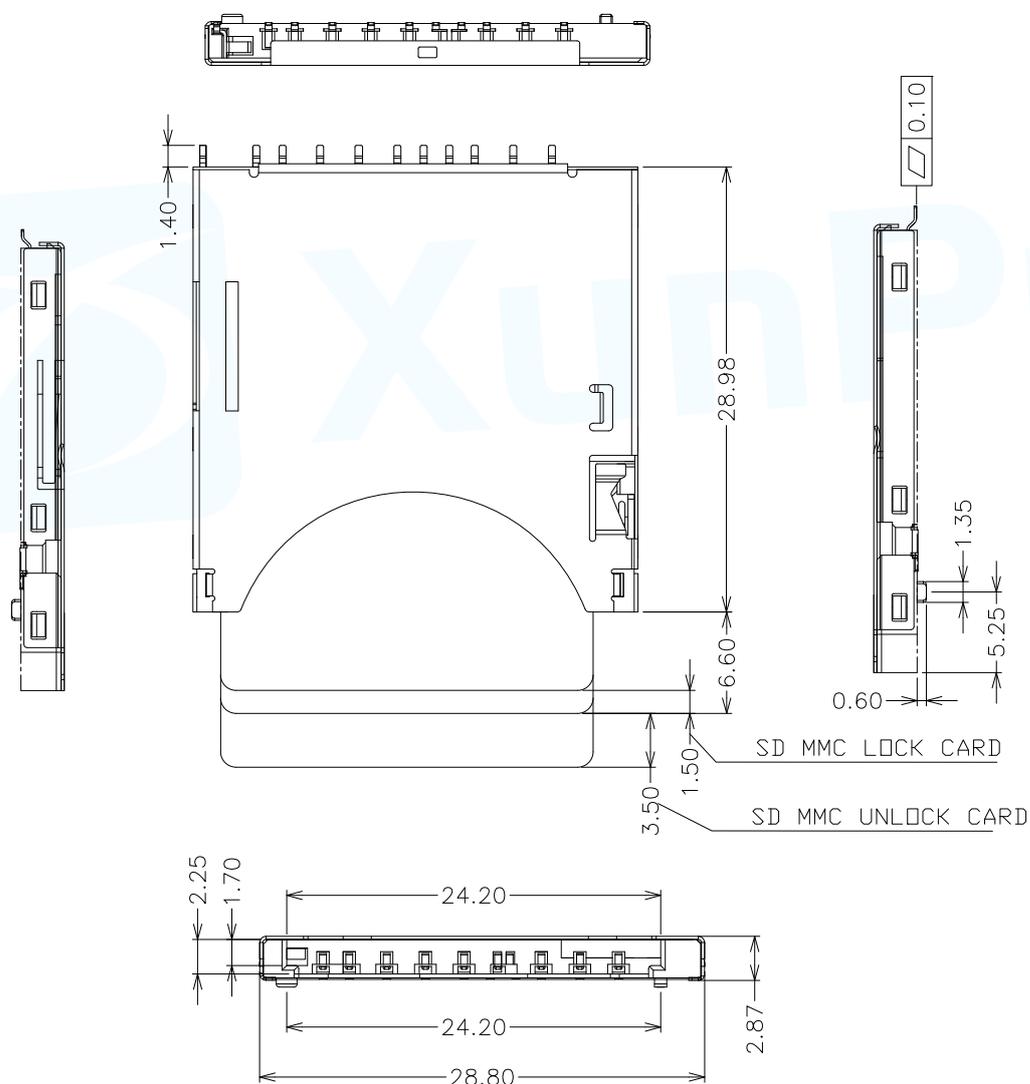
绝缘电阻(Insulation resistance): 1000MΩ min.

最小包装(Minimum packing): 400/PCS

## 外形尺寸(UNIT:MM) / Size Chart

[www.xunpudianzi.com](http://www.xunpudianzi.com)

更多资料请参考技术选型档!



## NOTES

### 1.MATERIAL

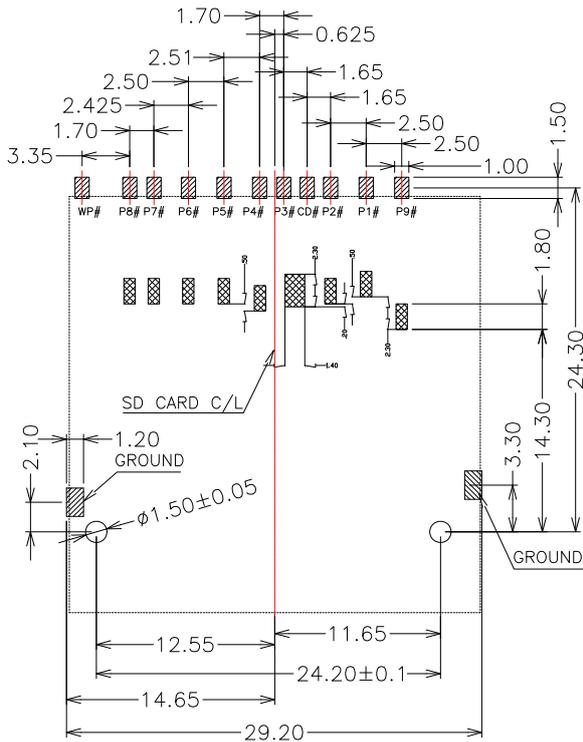
HOUSING: HIGH TEMPERATURE THERMOPLASTLC.  
CONTACT: COPPER ALLOY.  
SHELL: COPPER ALLOY.

### 2.PLATING

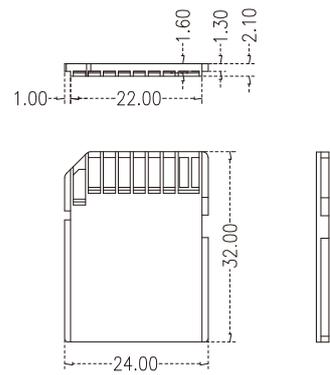
CONTACT AREA: GOLD PLATED ON CONTACT AREA.  
SOLDER TAIL: 100u' MIN Sn PLATED  
SHELL SOLDER AREA GOLD PLATED ON NICKEL UNDERPLATED.

### 3.SPECIFICATION

CONTACT RESISTANCE: 40 mOHMS  
DIELECTRIC WITHSTANDING VOLTAGE: 500VAC MegOHMS  
INSULATION RESISTANCE: 100 MegOHMS



● SD CARD

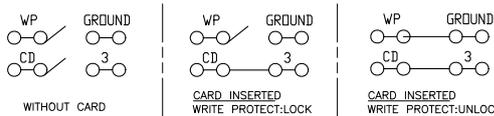


● 引脚定义/Pin Definition

PIN#	NAME	TYPE	DESCRIPTION
1#	CD/DAT3	I/O/PP	Command/Response
2#	CMD	PP	Supply voltage
3#	VSS1	S	Supply voltage ground
4#	VDD	S	Supply voltage
5#	CLK	I	Clock
6#	VSS2	S	Supply voltage ground
7#	DAT0	I/O/PP	Date Line(Bit0)
8#	DAT1	I/O/PP	Date Line(Bit1)
9#	DAT2	I/O/PP	Date Line(Bit2)

PCB 焊盘区 (PAD AREA)

禁区 (KEEP OUT AREA)



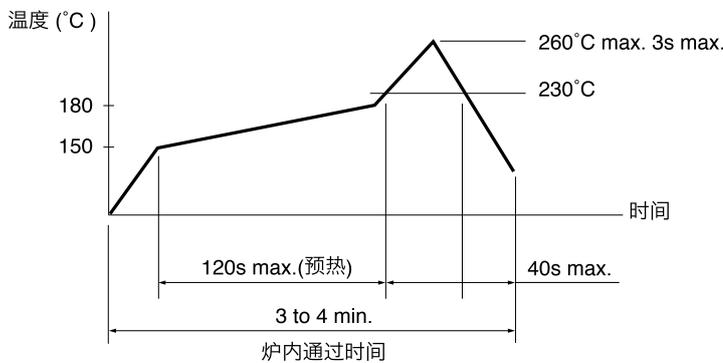
Circuit Diagram for Detect Switch

RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE ±0.05

焊接条件 / Welding conditions

● 回流焊/Reflow soldering

适用表面贴装型产品/Applicable to surface mount products  
温度分布/Temperature distribution



● 手焊式/Hand welding

项目/Project	条件/condition
焊接温度 Welding temperature	350°C max.
持续焊接时间 Continuous welding time	3s max.
焊剂斗容量 Flux bucket capacity	60W max.

● 浸焊式/Immersion soldering

项目/Project	条件/condition
助焊剂附着量 Flux adhesion	不附着于零部件贴装面的程度 Not attached to the mounting surface of components
预热温度 Preheating temperature	印刷电路板焊接面的周围温度 100°C max. The temperature around the welding surface of PCB is 100 °C max
预热温度时间 Preheat temperature time	60s max.
焊接温度 welding temperature	260°C max.
焊接浸渍时间 Welding immersion time	5s max.
焊接次数 Welding times	2 times max.

注:

1. 加热方式:以远红外线上下加热方式。
2. 温度测量:用Φ0.1~0.2的 CA(K)或 CC(T)测量位置在焊接连接部(锡/铜箔面)。
3. 固定方式:采用耐热胶带。